NPN Transistor Bare Die – TIP112

Rev 1.0
22/08/23

Bipolar Darlington Power Transistor in bare die form
Complement to PNP TIP117

Features:

- Collector current up to 2A
- Low V_{CE}(sat)
- Very high h_{FE}
- Solderable back metal
- High Reliability tested grades for Military + Space

Ordering Information:

The following part suffixes apply:

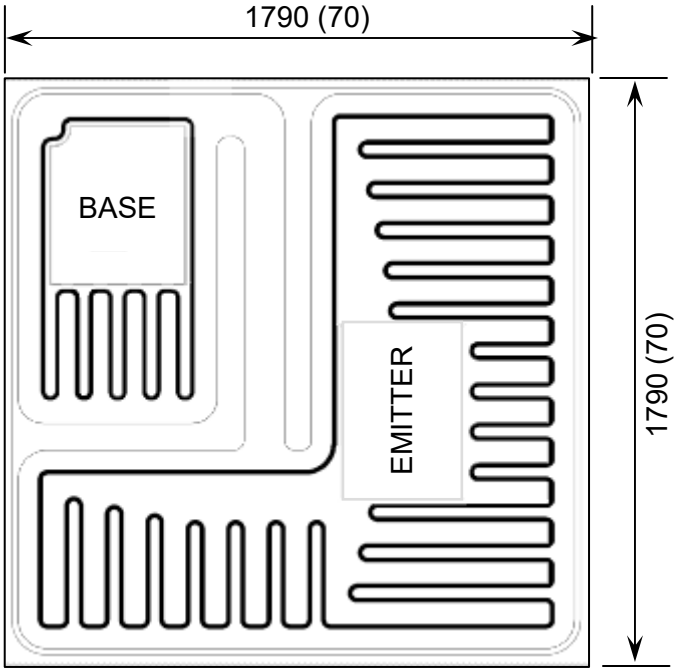
- No suffix - Commercial grade die
- "**H**" – Hi-rel grade die + MIL-STD-38534 Class H LAT
- "**K**" – Hi-rel grade die + MIL-STD-38534 Class K LAT.

LAT = Lot acceptance Test.

For information on Hi-Rel LAT flows please see below.

www.siliconsupplies.com\bare-die-lot-qualification

Die Dimensions in µm (mils)



DIE BACK = COLLECTOR

Supply Formats:

- Default – Die in Waffle Pack (100 per tray capacity)
- Sawn Wafer on Tape – Specific request
- Unsawn Wafer – Specific request
- With additional electrical selection – Specific request
- Sawn as pairs or adjacent pair pick – Specific request

Mechanical Specification

Die Size (Excluding Saw Street)	1790 x 1790 70.47 x 70.47	µm mils
Emitter Pad Size	374 x 524 14.72 x 20.63	µm mils
Base Pad Size	408 x 578 16.06 x 22.76	µm mils
Die Thickness	260 (±25) 10.2 (±1)	µm mils
Top Metal Composition	Al	
Back Metal Composition	Ti/Ni/Ag	

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Absolute Maximum Ratings T_A = 25°C unless otherwise stated

PARAMETER	SYMBOL	VALUE	UNIT
Collector-Base Voltage	V_{CBO}	100	V
Collector-Emitter Voltage	V_{CEO}	100	V
Emitter-Base Voltage	V_{EBO}	5	V
Collector Current - Continuous	I_C	2	A
Collector Current – Peak (t_P < 5ms)	I_{CM}	4	
Base Current	I_B	50	mA
Junction Temperature	T_J	150	°C
Storage Temperature	T_{stg}	-65 to 150	°C

Electrical Characteristics T_A = 25°C unless otherwise stated

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS						
Collector-Emitter Sustaining Voltage[1]	$V_{CEO(SUS)}$	I_B = 0, I_C = 30mA	100	-	-	V
Emitter-Base Breakdown Voltage	$V_{(BR)EBO}$	I_C = 0	5	-	-	V
Collector Cut-off Current	I_{CEO}	V_{CE} = 50V, I_B = 0	-	-	2	mA
Emitter Cut-off Current	I_{EBO}	V_{EB} = 5V, I_C = 0	-	-	2	mA
Collector Cut-off Current	I_{CBO}	V_{CB} = 100V, I_E = 0	-	-	1	mA
ON CHARACTERISTICS						
Forward-Current Transfer Ratio[1]	h_{FE}	I_C = 1A, V_{CE} = 4V	1000	-	-	-
		I_C = 2A, V_{CE} = 4V	500	-	-	-
Collector-Emitter Saturation Voltage[1]	$V_{CE(sat)}$	I_C = 2A, I_B = 8mA	-	-	2	V
Base-Emitter Saturation Voltage[1]	$V_{BE(on)}$	I_C = 2A, V_{CE} = 4V	-	-	2.8	V
SMALL SIGNAL CHARACTERISTICS[2]						
Small-Signal Current Gain	h_{fe}	V_{CE} = 10V, I_C = 0.75A, f = 1MHz	25	-	-	-
Output Capacitance	C_{ob}	V_{CB} = 10V, I_E = 0, f = 0.1MHz	-	-	250	pF

1. Pulsed duration = 300 µs, duty cycle ≤2.0%
2. Not production testing in die form, characterized by chip design and package verification